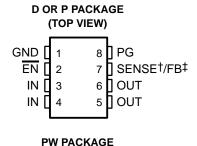
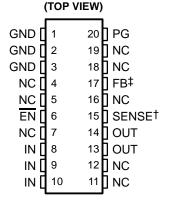
- Available in 5-V, 4.85-V, and 3.3-V
 Fixed-Output and Adjustable Versions
- Very Low-Dropout Voltage . . . Maximum of 32 mV at I_O = 100 mA (TPS7150)
- Very Low Quiescent Current Independent of Load . . . 285 μA Typ
- Extremely Low Sleep-State Current 0.5 μA Max
- 2% Tolerance Over Specified Conditions For Fixed-Output Versions
- Output Current Range of 0 mA to 500 mA
- TSSOP Package Option Offers Reduced Component Height for Space-Critical Applications
- Power-Good (PG) Status Output

description

The TPS71xx integrated circuits are a family of micropower low-dropout (LDO) voltage regulators. An order of magnitude reduction in dropout voltage and quiescent current over conventional LDO performance is achieved by replacing the typical pnp pass transistor with a PMOS device.





NC – No internal connection † SENSE – Fixed voltage options only (TPS7133, TPS7148, and TPS7150) ‡ FB – Adjustable version only (TPS7101)

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (maximum of 32 mV at an output current of 100 mA for the TPS7150) and is directly proportional to the output current (see Figure 1). Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and remains independent of output loading (typically 285 μ A over the full range of output current, 0 mA to 500 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems. The LDO family also features a sleep mode; applying a TTL high signal to $\overline{\text{EN}}$ (enable) shuts down the regulator, reducing the quiescent current to 0.5 μ A maximum at $T_{\text{L}} = 25^{\circ}\text{C}$.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

description (continued)

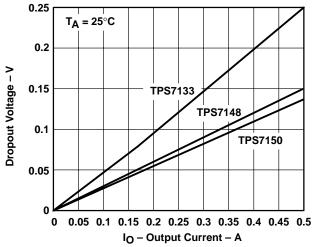


Figure 1. Dropout Voltage Versus Output Current

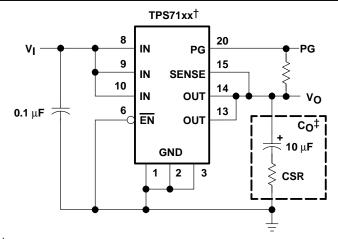
Power good (PG) reports low output voltage and can be used to implement a power-on reset or a low-battery indicator.

The TPS71xx is offered in 3.3-V, 4.85-V, and 5-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.2 V to 9.75 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges (3% for adjustable version). The TPS71xx family is available in PDIP (8 pin), SO (8 pin), and TSSOP (20-pin) packages. The TSSOP has a maximum height of 1,2 mm.

AVAILABLE OPTIONS

т.	OUTP	JT VOLT (V)	AGE	PAG	CKAGED DEVICE	:S	CHIP FORM
TJ	MIN	TYP	MAX	SMALL OUTLINE (D)	PLASTIC DIP (P)	TSSOP (PW)	(Y)
	4.9	5	5.1	TPS7150QD	TPS7150QP	TPS7150QPW	TPS7150Y
	4.75	4.85	4.95	TPS7148QD	TPS7148QP	TPS7148QPW	TPS7148Y
-40°C to 125°C	3.23	3.3	3.37	TPS7133QD	TPS7133QP	TPS7133QPW	TPS7133Y
		ljustable ¹ V to 9.75		TPS7101QD	TPS7101QP	TPS7101QPW	TPS7101Y

[†]The D and PW packages are available taped and reeled. Add R suffix to device type (e.g., TPS7150QDR). The TPS7101Q is programmable using an external resistor divider (see application information). The chip form is tested at 25°C.

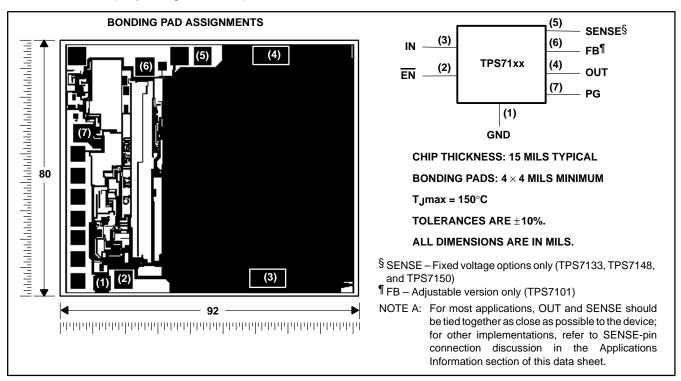


- † TPS7133, TPS7148, TPS7150 (fixed-voltage options)
- [‡] Capacitor selection is nontrivial. See application information section for details.

Figure 2. Typical Application Configuration

TPS71xx chip information

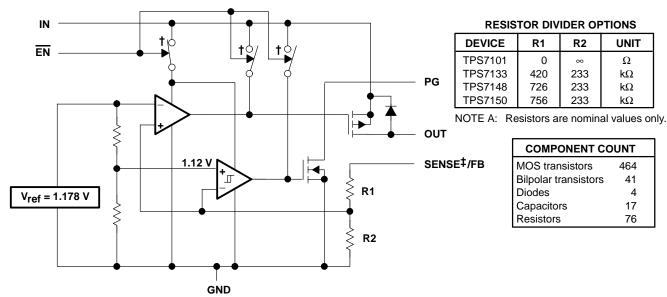
These chips, when properly assembled, display characteristics similar to the TPS71xxQ. Thermal compression or ultrasonic bonding may be used on the doped aluminum bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.



TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

functional block diagram



[†] Switch positions are shown with EN low (active).

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Input voltage range¶, V _I , PG, SENSE, EN	0.3 V to 11 V
Output current, I _O	2 A
Continuous total power dissipation	See Dissipation Rating Tables 1 and 2
Operating virtual junction temperature range, T _J	–55°C to 150°C
Storage temperature range, T _{Stq}	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[§] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE 1 - FREE-AIR TEMPERATURE (see Figure 3)#

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	145 mW
Р	1175 mW	9.4 mW/°C	752 mW	235 mW
PWII	700 mW	5.6 mW/°C	448 mW	140 mW

DISSIPATION RATING TABLE 2 - CASE TEMPERATURE (see Figure 4)#

PACKAGE	$T_C \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _C = 25°C	T _C = 70°C POWER RATING	T _C = 125°C POWER RATING
D	2188 mW	17.5 mW/°C	1400 mW	438 mW
Р	2738 mW	21.9 mW/°C	1752 mW	548 mW
PWII	4025 mW	32.2 mW/°C	2576 mW	805 mW

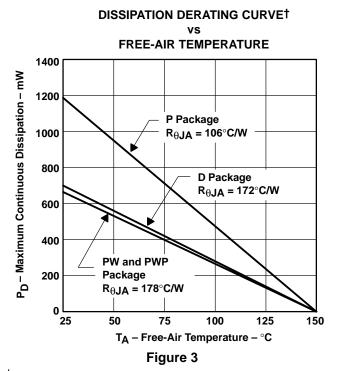
[#] Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. For guidelines on maintaining junction temperature within recommended operating range, see the Thermal Information section.

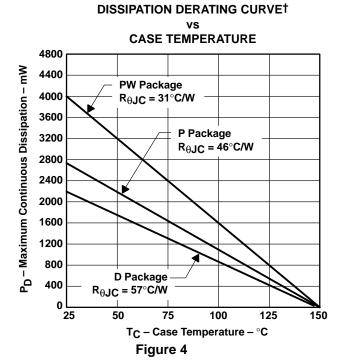
Refer to Thermal Information section for detailed power dissipation considerations when using the TSSOP packages.



[‡] For most applications, SENSE should be externally connected to OUT as close as possible to the device. For other implementations, refer to SENSE-pin connection discussion in Applications Information section.

[¶] All voltage values are with respect to network terminal ground.





[†] Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. For guidelines on maintaining junction temperature within recommended operating range, see the Thermal Information section.

recommended operating conditions

		MIN	MAX	UNIT
	TPS7101Q	2.5	10	
Innut valtage M.T	TPS7133Q	3.77	10] _v
Input voltage, V _I ‡	TPS7148Q	5.2	10	1 ^v
	TPS7150Q	5.33	10	1
High-level input voltage at EN, V _{IH}		2		V
Low-level input voltage at EN, V _{IL}			0.5	V
Output current range, IO		0	500	mA
Operating virtual junction temperature rar	ge, TJ	-40	125	°C

[‡] Minimum input voltage defined in the recommended operating conditions is the maximum specified output voltage plus dropout voltage at the maximum specified load range. Since dropout voltage is a function of output current, the usable range can be extended for lighter loads. To calculate the minimum input voltage for your maximum output current, use the following equation: $V_{I(min)} = V_{O(max)} + V_{DO(max load)}$. Because the TPS7101 is programmable, $v_{DO(max)}$ should be used to calculate $v_{DO(max)}$ before applying the above equation. The equation for calculating $v_{DO(max)}$ is given in Note 2 in the electrical characteristics table. The minimum value of 2.5 V is the absolute lower limit for the recommended input voltage range for the TPS7101.



TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted)

PARAMETER	TEST CONI	DITIONS‡	ТЈ		1Q, TPS 8Q, TPS		UNIT	
				MIN	TYP	MAX		
Ground current (active mode)	<u>EN</u> ≤ 0.5 V,	$V_{I} = V_{O} + 1 V_{A}$	25°C		285	350	μА	
Ground current (active mode)	$0~\text{mA} \leq I_{\mbox{O}} \leq 500~\text{mA}$		-40°C to 125°C			460	μΑ	
Input current (standby mode)	$\overline{EN} = VI,$	2.7 V ≤ V _I ≤ 10 V	25°C			0.5	μА	
mput current (standby mode)	\square N = V ,	2.7 V ≤ V ≤ 10 V	-40°C to 125°C			2	μΑ	
Output current limit	V _O = 0,	V _I = 10 V	25°C		1.2	2	A	
Output current iiniit	V() = 0,	V - 10 V	-40°C to 125°C			2	A .	
Pass-element leakage current in standby	ent leakage current in standby $\overline{EN} = V_1$, $2.7 \text{ V} \le$	2.7 V ≤ V _I ≤ 10 V	25°C			0.5	μА	
mode	\square N = V ,	2.1 V 2 V 2 10 V	-40°C to 125°C			1	μΑ	
PG leakage current	Normal operation,	Vpg = 10 V	25°C		0.02	0.5	μΑ	
	Normal operation,		-40°C to 125°C			0.5	μΑ	
Output voltage temperature coefficient			-40°C to 125°C		61	75	ppm/°C	
Thermal shutdown junction temperature					165		°C	
ENLIGHT AND ACTOR Albert and all and all and all all all and all all all all all all all all all al	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 6 \text{ V}$		-40°C to 125°C	2			V	
EN logic high (standby mode)	6 V ≤ V _I ≤ 10 V		-40 C to 125 C	2.7]	
EN la via la confection and de)	271/21/2401/		25°C			0.5	V	
EN logic low (active mode)	2.7 V ≤ V _I ≤ 10 V		-40°C to 125°C			0.5	l ^v	
EN hysteresis voltage			25°C		50		mV	
<u> </u>	01/21/22401/	01/21/2401/	25°C	-0.5		0.5		
EN input current	0 V ≤ V _I ≤ 10 V	$0 \text{ V} \leq \text{V}_{\text{I}} \leq 10 \text{ V}$	-40°C to 125°C	-0.5		0.5	μΑ	
Minimum V. for active page clares			25°C		2.05	2.5	V	
Minimum V _I for active pass element			-40°C to 125°C			2.5	ľ	
Minimum V. for valid DC	I 200 ·· A	I 200 ·· A	25°C		1.06	1.5	\ ,,	
Minimum V _I for valid PG	I _{PG} = 300 μA	I _{PG} = 300 μA	-40°C to 125°C			1.9	V	

[†] CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to CO.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7101 electrical characteristics at I_O = 10 mA, V_I = 3.5 V, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , FB shorted to OUT at device leads (unless otherwise noted)

DADAMETER	TEST COL	UDITIONST	т.	T	TPS7101Q		
PARAMETER	TEST COI	NDITIONS‡	TJ	MIN	TYP	MAX	UNIT
Reference voltage (measured at FB	V _I = 3.5 V,	I _O = 10 mA	25°C		1.178		V
with OUT connected to FB)	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$ See Note 1	$5~\text{mA} \leq I_{\mbox{O}} \leq 500~\text{mA},$	-40°C to 125°C	1.143		1.213	V
Reference voltage temperature coefficient			-40°C to 125°C		61	75	ppm/°C
	V: 0.4.V	50 A < l = < 450 m A	25°C		0.7	1	
	V _I = 2.4 V,	$50 \mu\text{A} \le I_{\text{O}} \le 150 \text{mA}$	-40°C to 125°C			1	1
Pass-element series resistance	V _I = 2.4 V,	150 mA ≤ I _O ≤ 500	25°C		0.83	1.3	
	V = 2.4 V,	mA	-40°C to 125°C			1.3	Ω
(see Note 2)	V. – 2 0 V	50 u A < lo < 500 mA	25°C		0.52	0.85] \(\(\(\) \)
	V _I = 2.9 V,	$50 \mu\text{A} \le I_{\text{O}} \le 500 \text{mA}$	-40°C to 125°C			0.85]
	V _I = 3.9 V,	$50~\mu\text{A} \leq I_{\mbox{O}} \leq 500~m\text{A}$	25°C		0.32]
	V _I = 5.9 V,	$50~\mu A \leq I_O \leq 500~mA$	25°C		0.23		
Input regulation	$V_I = 2.5 \text{ V to } 10 \text{ V},$	50 μ A ≤ I _O ≤ 500 mA,	25°C			18	mV
Imput regulation	See Note 1		-40°C to 125°C			25	IIIV
	$I_0 = 5 \text{ mA to } 500 \text{ mA},$		25°C			14	mV
	See Note 1		-40°C to 125°C			25	1111
Output regulation	$I_0 = 50 \mu\text{A} \text{ to } 500 \text{mA},$		25°C			22	mV
	See Note 1		-40°C to 125°C			54	1117
		lo = 50 !! A	25°C	48	59		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	44			dB
Rippie rejection	1 = 120112	$I_0 = 500 \text{ mA},$	25°C	45	54] ab
		See Note 1	-40°C to 125°C	44			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√Hz
		$C_O = 4.7 \mu F$	25°C		95		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	$C_{O} = 10 \mu F$	25°C		89		μVrms
	00111 = 122	C _O = 100 μF	25°C		74		
PG trip-threshold voltage§	VFB voltage decreasing	g from above V _{PG}	-40°C to 125°C	1.101		1.145	V
PG hysteresis voltage§	Measured at VFB		25°C		12		mV
			25°C		0.1	0.4	<u>,,</u>
PG output low voltage§	$I_{PG} = 400 \mu A$	V _I = 2.13 V	-40°C to 125°C			0.4	'
			25°C	-10	0.1	10	,
FB input current			-40°C to 125°C	-20		20	nA

TCSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

 $V_{DO} = I_O \cdot r_{DS(on)}$

 $r_{DS(on)}$ is a function of both output current and input voltage. The parametric table lists $r_{DS(on)}$ for $V_I = 2.4$ V, 2.9 V, 3.9 V, and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 2.5 V, 3 V, 4 V, and 6 V, respectively. For other programmed values, refer to Figure 26.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Output voltage programmed to 2.5 V with closed-loop configuration (see application information).

NOTES: 1. When V_I < 2.9 V and I_O > 150 mA simultaneously, pass element r_{DS(on)} increases (see Figure 27) to a point such that the resulting dropout voltage prevents the regulator from maintaining the specified tolerance range.

^{2.} To calculate dropout voltage, use equation:

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

TPS7133 electrical characteristics at I_O = 10 mA, V_I = 4.3 V, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

PARAMETER	TEST CON	IDITIONS‡	TJ		PS71330	ì	UNIT
TANAMETER	1201 001		.,	MIN	TYP	MAX	J
Output voltage	$V_{I} = 4.3 V$,	I _O = 10 mA	25°C		3.3		V
- Cutput voltage	$4.3 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$5 \text{ mA} \le I_O \le 500 \text{ mA}$	-40°C to 125°C	3.23		3.37	, v
	IO = 10 mA,	V _I = 3.23 V	25°C		4.5	7	
	10 = 10 1117.	V = 3.23 V	-40°C to 125°C			8	
Dropout voltage	IO = 100 mA,	V _I = 3.23 V	25°C		47	60	m∨
Dropout voltage	10 = 100 mA,	V = 3.23 V	-40°C to 125°C			80	1111
	IO = 500 mA,	V _I = 3.23 V	25°C		235	300	
	IO = 500 IIIA,	V = 3.23 V	-40°C to 125°C			400	
Dana alamant agrica registance	(3.23 V – V _O)/I _O ,	V _I = 3.23 V,	25°C		0.47	0.6	Ω
Pass-element series resistance	I _O = 500 mA	•	-40°C to 125°C			0.8	12
land the state of	V 40V/+=40V/	50 μA ≤ I _O ≤ 500 mA	25°C			20	mV
Input regulation	$V_I = 4.3 \text{ V to } 10 \text{ V},$	20 hα ≥ 10 ≥ 200 mα	-40°C to 125°C			27	mv
	I _O = 5 mA to 500 mA,		25°C		21	38	mV
			-40°C to 125°C			75	mv
Output regulation	In E0 A to E00 mA		25°C		30	60	mV
	$I_O = 50 \mu A \text{ to } 500 \text{ mA},$	$4.3 \text{ V} \leq \text{V} \leq 10 \text{ V}$	-40°C to 125°C			120	mv
		15 50 4	25°C	43	54		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	40			dB
Rippie rejection	T = 120 HZ	1 500 mA	25°C	39	49		иь
		I _O = 500 mA	-40°C to 125°C	36			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√ Hz
		C _O = 4.7 μF	25°C		274		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	C _O = 10 μF	25°C		228		μVrms
	001(1 = 1 32	C _O = 100 μF	25°C		159		1
PG trip-threshold voltage	VO voltage decreasing	from above V _{PG}	-40°C to 125°C	2.868		3	V
PG hysteresis voltage			25°C		35		mV
DC systematic consistence	1 4 4	V 0.0V	25°C		0.22	0.4	.,
PG output low voltage	$I_{PG} = 1 \text{ mA},$	V _I = 2.8 V	-40°C to 125°C			0.4	V

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7148 electrical characteristics at I $_{O}$ = 10 mA, V $_{I}$ = 5.85 V, $\overline{\text{EN}}$ = 0 V, C $_{O}$ = 4.7 μ F/CSR † = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

24244555	TEOT 001	IDITIONS [†]	_	TF	PS71480	2	
PARAMETER	TEST CON	IDITIONS+	TJ	MIN	TYP	MAX	UNIT
Output valtage	V _I = 5.85 V,	I _O = 10 mA	25°C		4.85		V
Output voltage	$5.85 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$5 \text{ mA} \le I_O \le 500 \text{ mA}$	-40°C to 125°C	4.75		4.95	V
	In 10 mA	V. 475 V	25°C		2.9	6	
	I _O = 10 mA,	V _I = 4.75 V	-40°C to 125°C			8	
Duamantinaltana	Jo - 100 mA	V. – 4.75 V	25°C		30	37	m∨
Dropout voltage	I _O = 100 mA,	V _I = 4.75 V	-40°C to 125°C			54	IIIV
	In - 500 mA	V _I = 4.75 V	25°C		150	180	
	$I_{O} = 500 \text{ mA},$	V = 4.75 V	-40°C to 125°C			250	
Dans element perios registence	(4.75 V – V _O)/I _O ,	V _I = 4.75 V,	25°C		0.32	0.35	Ω
Pass-element series resistance	$I_{O} = 500 \text{ mA}$	•	-40°C to 125°C			0.52	\$2
lanut regulation	V. 5.95 V to 40 V	$50 \mu A \le I_{O} \le 500 \text{mA}$	25°C			27	mV
Input regulation	$V_{I} = 5.85 \text{ V to } 10 \text{ V},$	30 μΑ ≤ 10 ≤ 300 111Α	-40°C to 125°C			37	mv
I [↑]	lo = 5 mA to 500 mA	5.85 V ≤ V _I ≤ 10 V	25°C		12	42	mV
	IO = 5 mA to 500 mA,		-40°C to 125°C			80	mv
Output regulation	$I_{O} = 50 \mu\text{A} \text{ to } 500 \text{mA},$	E 95 V < V < 10 V	25°C		42	60	mV
	$IO = 50 \mu A to 500 mA$	5.85 V ≤ V ≤ 10 V	-40°C to 125°C			130	mv
		I. 50 A	25°C	42	53		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	39			dB
Kipple rejection	1 = 120112	I _O = 500 mA	25°C	39	50		ub
		10 = 300 IIIA	-40°C to 125°C	35			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√Hz
		$C_O = 4.7 \mu F$	25°C		410		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	C _O = 10 μF	25°C		328		μVrms
	03((1 = 1 \frac{1}{2})	C _O = 100 μF	25°C		212		1
PG trip-threshold voltage	VO voltage decreasing	from above V _{PG}	-40°C to 125°C	4.5		4.7	V
PG hysteresis voltage			25°C		50		mV
	1		25°C		0.2	0.4	ν,
PG output low voltage	IpG = 1.2 mA,	V _I = 4.12 V	-40°C to 125°C			0.4	V

[†]CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.

to C_O. ‡ Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

TPS7150 electrical characteristics at I_O = 10 mA, V_I = 6 V, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

DADAMETER	TEOT 001	TEST CONDITIONS‡		TF	PS71500	Q .	UNIT
PARAMETER	IEST CON	IDITIONS+	TJ	MIN	TYP	MAX	UNII
Output voltogo	V _I = 6 V,	I _O = 10 mA	25°C		5		V
Output voltage	$6 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$5~\text{mA} \leq I_{\mbox{O}} \leq 500~\text{mA}$	-40°C to 125°C	4.9		5.1	V
	IO = 10 mA,	V _I = 4.88 V	25°C		2.9	6	
	IO = 10 IIIA,	V = 4.00 V	-40°C to 125°C			8	
Drangut valtage	IO = 100 mA,	V _I = 4.88 V	25°C		27	32	m∨
Dropout voltage	10 = 100 IIIA,	V = 4.00 V	-40°C to 125°C			47	1117
	IO = 500 mA,	V _I = 4.88 V	25°C		146	170	
	IO = 500 IIIA,	V = 4.00 V	-40°C to 125°C			230	
Pass-element series resistance	(4.88 V – V _O)/I _O ,	V _I = 4.88 V,	25°C		0.29	0.32	Ω
Fass-element series resistance	$I_{O} = 500 \text{ mA}$		-40°C to 125°C			0.47	52
Input regulation	V _I = 6 V to 10 V,	50 μA ≤ I _O ≤ 500 mA	25°C			25	mV
Input regulation	V = 0 V tO 10 V,	30 μA 3 10 3 300 111A	-40°C to 125°C			32	IIIV
Output so sulption	$I_O = 5$ mA to 500 mA,	6 V ≤ V _I ≤ 10 V	25°C		30	45	mV
			-40°C to 125°C			86	
Output regulation	10 FO A to FOO mA	01/ 11/ 1401/	25°C		45	65	mV
	$I_O = 50 \mu\text{A} \text{ to } 500 \text{mA},$	6 ∧ ≥ ∧ ≥ 10 v	-40°C to 125°C			140	IIIV
		In 50 A	25°C	45	55		
Ripple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	40			dB
Ripple rejection	I = 120 HZ	I- 500 mA	25°C	42	52		иь
		I _O = 500 mA	-40°C to 125°C	36			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√ Hz
		C _O = 4.7 μF	25°C		430		
Output noise voltage	10 Hz \leq f \leq 100 kHz, CSR [†] = 1 Ω	C _O = 10 μF	25°C		345		μVrms
OOK1 = 1 52	C _O = 100 μF	25°C		220			
PG trip-threshold voltage	VO voltage decreasing	from above V _{PG}	-40°C to 125°C	4.55		4.75	V
PG hysteresis voltage			25°C		53		mV
DO autout lawarely	4.0	V 405.V	25°C		0.2	0.4	.,
PG output low voltage	$I_{PG} = 1.2 \text{ mA},$	V _I = 4.25 V	-40°C to 125°C			0.4	V

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 $\Omega,$ T $_{J}$ = 25°C, SENSE/FB shorted to OUT (unless otherwise noted)

PARAMETER	TEST CONDITIONS‡	TPS7101Y, TPS7133Y TPS7148Y, TPS7150Y	UNIT
		MIN TYP MAX	
Ground current (active mode)	$\overline{\text{EN}} \le 0.5 \text{ V},$ $V_{\text{I}} = V_{\text{O}} + 1 \text{ V},$ $0 \text{ mA} \le I_{\text{O}} \le 500 \text{ mA}$	285	μΑ
Output current limit	$V_0 = 0,$ $V_1 = 10 \text{ V}$	1.2	Α
PG leakage current	Normal operation, V _{PG} = 10 V	0.02	μΑ
Thermal shutdown junction temperature		165	°C
EN hysteresis voltage		50	mV
Minimum V _I for active pass element		2.05	V
Minimum V _I for valid PG	I _{PG} = 300 μA	1.06	V

PARAMETER	TEOT 06	TEST CONDITIONS‡		S7101Y	,	UNIT
PARAMETER	l iESI CC	ONDITIONS+	MIN	TYP	MAX	UNII
Reference voltage (measured at FB with OUT connected to FB)	V _I = 3.5 V,	I _O = 10 mA		1.178		V
	V _I = 2.4 V,	$50~\mu\text{A} \leq \text{I}_{O} \leq 150~\text{mA}$		0.7		
	V _I = 2.4 V,	$150~\text{mA} \leq I_{\mbox{O}} \leq 500~\text{mA}$		0.83		
Pass-element series resistance (see Note 2)	$V_{\parallel} = 2.9 \text{ V},$	$50~\mu\text{A} \leq \text{I}_{O} \leq 500~\text{mA}$		0.52		Ω
	V _I = 3.9 V,	$50~\mu\text{A} \leq \text{I}_{\mbox{O}} \leq 500~\text{mA}$		0.32		
	V _I = 5.9 V,	$50~\mu\text{A} \leq \text{I}_{\mbox{O}} \leq 500~\text{mA}$		0.23		
Input regulation	V _I = 2.5 V to 10 V, See Note 1	$50 \mu A \le I_O \le 500 mA$,			18	mV
Outrot so sulption	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$ See Note 1	$I_O = 5$ mA to 500 mA,			14	mV
Output regulation	$2.5 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$ See Note 1	$I_O = 50 \mu A \text{ to } 500 \text{ mA},$			22	mV
Ripple rejection	V _I = 3.5 V, I _O = 50 μA	f = 120 Hz,		59		dB
Output noise-spectral density	V _I = 3.5 V,	f = 120 Hz		2		μV/√ Hz
	V _I = 3.5 V,	$C_{O} = 4.7 \mu F$		95		
Output noise voltage	10 Hz ≤ f ≤ 100 kHz,	C _O = 10 μF		89		μVrms
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF	74			
PG hysteresis voltage§	V _I = 3.5 V,	Measured at V _{FB}		12		mV
PG output low voltage§	V _I = 2.13 V,	I _{PG} = 400 μA		0.1		V
FB input current	V _I = 3.5 V	V _I = 3.5 V		0.1		nA

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

2. To calculate dropout voltage, use equation:

 $V_{DO} = I_O \cdot r_{DS(on)}$

 $r_{DS(on)}$ is a function of both output current and input voltage. The parametric table lists $r_{DS(on)}$ for $V_I = 2.4$ V, 2.9 V, 3.9 V, and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 2.5 V, 3 V, 4 V, and 6 V, respectively. For other programmed values, refer to Figure 26.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

[§] Output voltage programmed to 2.5 V with closed-loop configuration (see application information).

NOTES: 1. When V_I < 2.9 V and I_O > 150 mA simultaneously, pass element r_{DS(on)} increases (see Figure 27) to a point such that the resulting dropout voltage prevents the regulator from maintaining the specified tolerance range.

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , T $_{J}$ = 25°C , SENSE shorted to OUT (unless otherwise noted) (continued)

DADAMETED		NDITIONS [†]	TF	UNIT		
PARAMETER	l lesi co	TEST CONDITIONS [‡]				UNIT
Output voltage	$V_{I} = 4.3 V$	I _O = 10 mA		3.3		V
	$V_{I} = 3.23 \text{ V},$	I _O = 10 mA		0.02		
Dropout voltage	$V_{I} = 3.23 V$	I _O = 100 mA		47		mV
	$V_{I} = 3.23 V$	$I_{O} = 500 \text{ mA}$		235		
Pass-element series resistance	$(3.23 \text{ V} - \text{V}_{\text{O}})/\text{I}_{\text{O}},$ $\text{I}_{\text{O}} = 500 \text{ mA}$	V _I = 3.23 V,		0.47		Ω
Output regulation	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$	$I_O = 5$ mA to 500 mA		21		mV
Output regulation	$4.3 \text{ V} \le \text{V}_{\text{I}} \le 10 \text{ V},$	$I_{O} = 50 \mu\text{A}$ to 500 mA		30		mV
Ripple rejection	V _I = 4.3 V,	ΙΟ = 50 μΑ	54			dB
Rippie rejection	f = 120 Hz	I _O = 500 mA	49			uБ
Output noise-spectral density	$V_{I} = 4.3 V$	f = 120 Hz		2		μV/√ Hz
	V _I = 4.3 V,	$C_{O} = 4.7 \mu\text{F}$		274		
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	228		μVrms	
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF		159		
PG hysteresis voltage	V _I = 4.3 V	-		35		mV
PG output low voltage	V _I = 2.8 V,	Ipg = 1 mA		0.22		V

DADAMETER	TEOT OC	NDITIONO†	TPS7148Y			LINUT
PARAMETER	lesi co	ONDITIONS‡	MIN	TYP	MAX	UNIT
Output voltage	V _I = 5.85 V,	I _O = 10 mA		4.85		V
	V _I = 4.75 V,	I _O = 10 mA		0.08		
Dropout voltage	V _I = 4.75 V,	I _O = 100 mA		30		mV
	V _I = 4.75 V,	I _O = 500 mA		150		
Pass-element series resistance	$(4.75 \text{ V} - \text{V}_{\text{O}})/\text{I}_{\text{O}},$ $\text{I}_{\text{O}} = 500 \text{ mA}$	V _I = 4.75 V,		0.32		Ω
Output to guilation	5.85 V ≤ V _I ≤ 10 V,	$I_O = 5$ mA to 500 mA	12			mV
Output regulation	$5.85 \text{ V} \le \text{V}_{I} \le 10 \text{ V},$	$I_O = 50 \mu A$ to 500 mA	42			mV
Dinnle rejection	V _I = 5.85 V,	ΙΟ = 50 μΑ	53 50			dB
Ripple rejection	f = 120 Hz	I _O = 500 mA				
Output noise-spectral density	V _I = 5.85 V,	f = 120 Hz		2		μV/√ Hz
	V _I = 5.85 V,	$C_{O} = 4.7 \mu F$		410		
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	328 212			μVrms
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF				1
PG hysteresis voltage	V _I = 5.85 V	-		50		mV
PG output low voltage	V _I = 4.12 V,	I _{PG} = 1.2 mA		0.2	0.4	V

[†] CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.



[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

electrical characteristics at I $_{O}$ = 10 mA, \overline{EN} = 0 V, C $_{O}$ = 4.7 $\mu\text{F/CSR}^{\dagger}$ = 1 Ω , T $_{J}$ = 25°C , SENSE shorted to OUT (unless otherwise noted) (continued)

DADAMETED	7507.0	NIDITIONS [†]	TF	TPS7150Y			
PARAMETER	TEST CO	TEST CONDITIONS [‡]				UNIT	
Output voltage	V _I = 6 V,	I _O = 10 mA		5		V	
	V _I = 4.88 V,	I _O = 10 mA		0.13			
Dropout voltage	$V_{I} = 4.88 V$	I _O = 100 mA		27		mV	
	$V_{I} = 4.88 V$	I _O = 500 μA		146			
Pass-element series resistance	$(4.88 \text{ V} - \text{V}_{\text{O}})/\text{I}_{\text{O}},$ $\text{I}_{\text{O}} = 500 \text{ mA}$	V _I = 4.88 V,		0.29		Ω	
Output regulation	6 V ≤ V _I ≤ 10 V,	$I_O = 5 \text{ mA to } 500 \text{ mA}$		30		mV	
Output regulation	6 V ≤ V _I ≤ 10 V,	$I_{O} = 50 \mu\text{A}$ to 500 mA		45		mV	
Dinale rejection	V _I = 6 V,	ΙΟ = 50 μΑ	55 52		dB		
Ripple rejection	f = 120 Hz	I _O = 500 mA					
Output noise-spectral density	V _I = 6 V,	f = 120 Hz		2		μV/√ Hz	
	V _I = 6 V,	C _O = 4.7 μF		430			
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	345			μVrms	
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF		220			
PG hysteresis voltage	V _I = 6 V			53		mV	
PG output low voltage	V _I = 4.25 V,	PG = 1.2 mA		0.2		V	

[†]CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

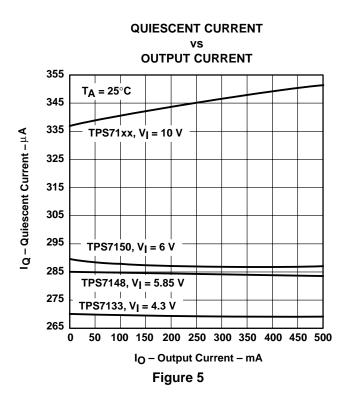


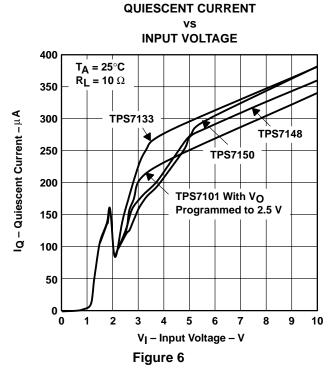
[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

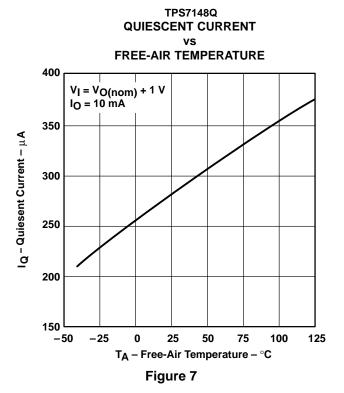
Table of Graphs

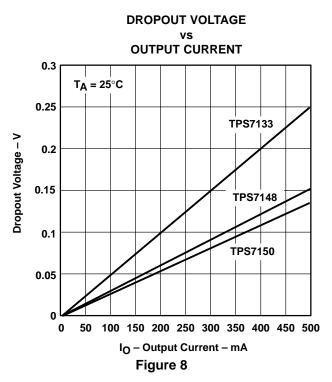
			FIGURE
		vs Output current	5
lQ	Quiescent current	vs Input voltage	6
		vs Free-air temperature	7
V_{DO}	Dropout voltage	vs Output current	8
ΔV_{DO}	Change in dropout voltage	vs Free-air temperature	9
ΔV_{O}	Change in output voltage	vs Free-air temperature	10
۷o	Output voltage	vs Input voltage	11
ΔV_{O}	Change in output voltage	vs Input voltage	12
			13
M-	Output valle as	Luc Quatro de companda	14
VO	Output voltage	vs Output current	15
			16
			17
	Disale seiseties		18
	Ripple rejection	vs Frequency	19
			20
			21
		_	22
	Output spectral noise density	vs Frequency	23
			24
rDS(on)	Pass-element resistance	vs Input voltage	25
R	Divider resistance	vs Free-air temperature	26
I(SENSE)	SENSE pin current	vs Free-air temperature	27
,	FB leakage current	vs Free-air temperature	28
M	Minimum input voltage for active-pass element	vs Free-air temperature	29
VI	Minimum input voltage for valid PG	vs Free-air temperature	30
I _{I(EN)}	Input current (EN)	vs Free-air temperature	31
, ,	Output voltage response from Enable (EN)		32
V_{PG}	Power-good (PG) voltage	vs Output voltage	33
			34
CSR	Compensation series resistance	vs Output current	35
000			36
CSR	Compensation series resistance	vs Added ceramic capacitance	37
000	0 " ' '		38
CSR	Compensation series resistance	vs Output current	39
000	Output and the section of the	and Added annual 2009	40
CSR	Compensation series resistance	vs Added ceramic capacitance	41





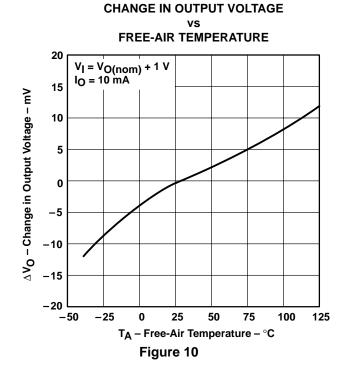


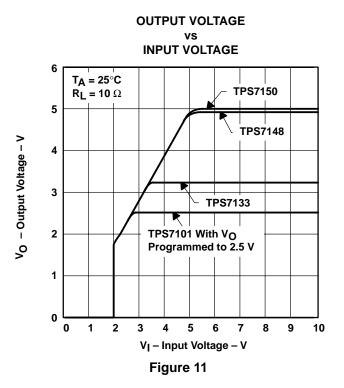


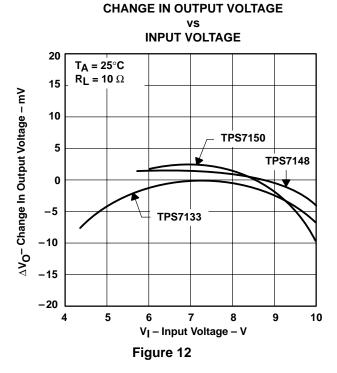


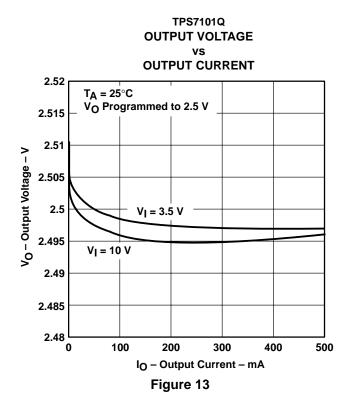
CHANGE IN DROPOUT VOLTAGE FREE-AIR TEMPERATURE 10 IO = 100 mA 8 Change in Dropout Voltage – mV 6 4 2 0 -2 -4 -6 -8 -10_50 -25 25 50 75 100 125 T_A - Free-Air Temperature - °C

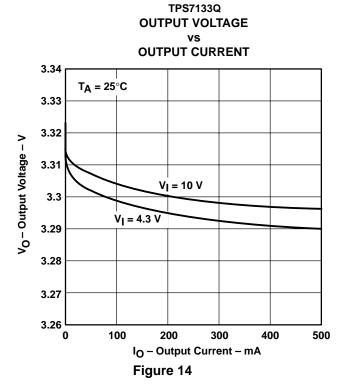
Figure 9

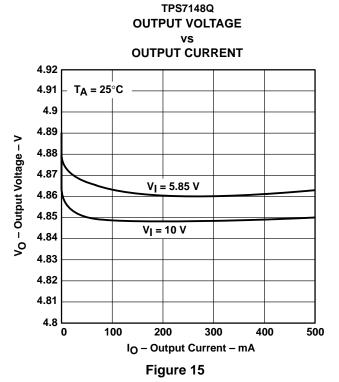


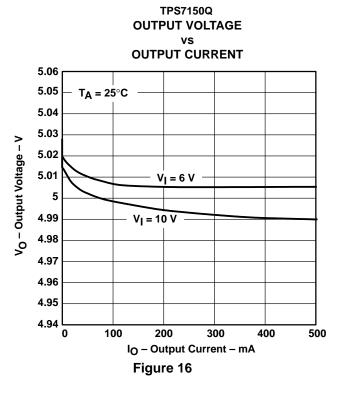












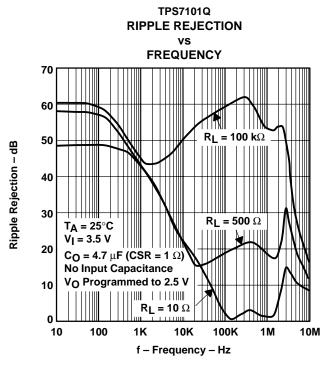
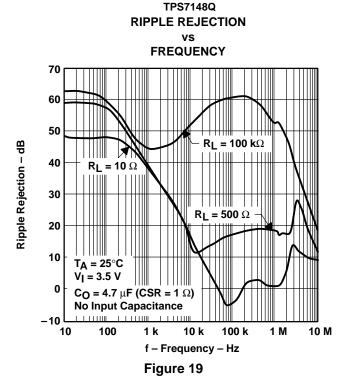
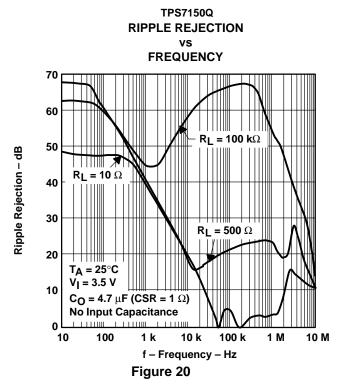


Figure 17



TPS7133Q RIPPLE REJECTION vs **FREQUENCY** 70 60 $R_L = 100 \text{ k}\Omega$ 50 Ripple Rejection – dB 40 30 $R_L = 500 \Omega$ 20 $R_L = 10 \Omega$ 10 $T_A = 25^{\circ}C$ $V_{I} = 3.5 V$ $C_0 = 4.7 \,\mu\text{F} (CSR = 1 \,\Omega)$ No Input Capacitance 100 10 k 10 100 k 1 M 10 M f - Frequency - Hz

Figure 18





TPS7133Q

OUTPUT SPECTRAL NOISE DENSITY

FREQUENCY

 $T_A = 25^{\circ}C$

 $V_{I} = 4.3 V$

 $C_0 = 10 \,\mu\text{F} (CSR = 1 \,\Omega)$

No Input Capacitance

 $C_0 = 4.7 \,\mu\text{F} \,(\text{CSR} = 1 \,\Omega)$

 $C_O = 100 \mu F (CSR = 1 \Omega)$

104

105

TYPICAL CHARACTERISTICS

TPS7101Q OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

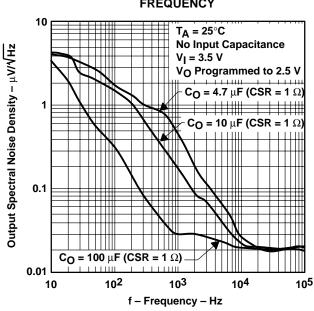


Figure 21

Output Spectral Noise Density – µV/VHz

0.01

10

10

Figure 22

102

TPS7148Q OUTPUT SPECTRAL NOISE DENSITY vs

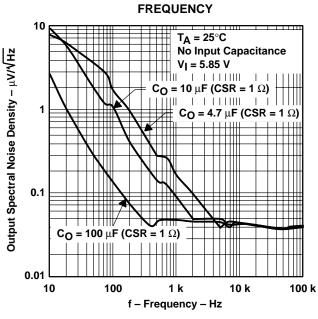


Figure 23

TPS7150Q OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

103

f - Frequency - Hz

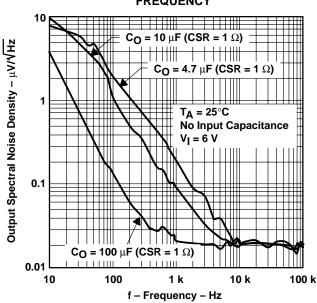
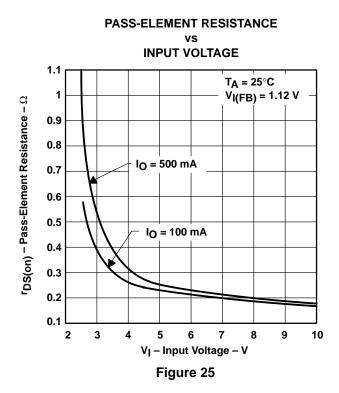
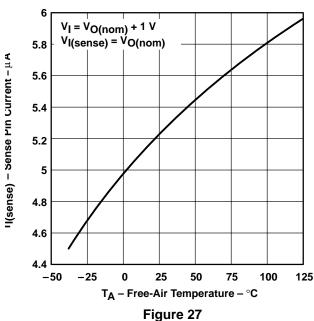


Figure 24

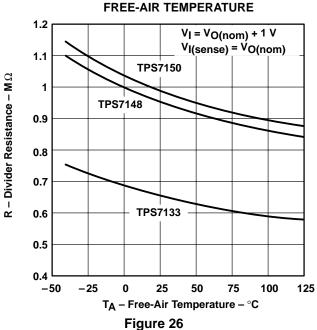




FREE-AIR TEMPERATURE

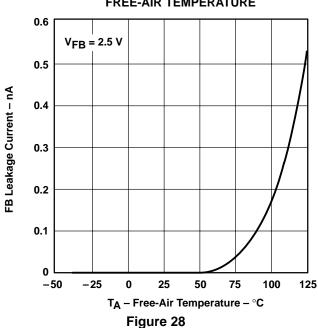


DIVIDER RESISTANCE vs EDEE AIR TEMPERATURE



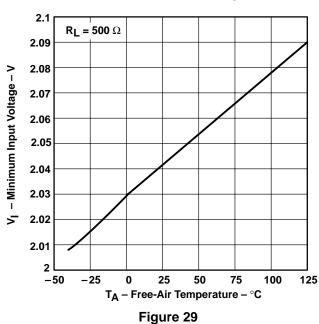
ADJUSTABLE VERSION FB LEAKAGE CURRENT

vs FREE-AIR TEMPERATURE



MINIMUM INPUT VOLTAGE FOR ACTIVE PASS ELEMENT

FREE-AIR TEMPERATURE



MINIMUM INPUT VOLTAGE FOR VALID POWER GOOD (PG)

vs FREE-AIR TEMPERATURE

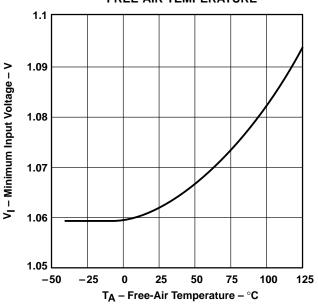


Figure 30

EN INPUT CURRENT vs

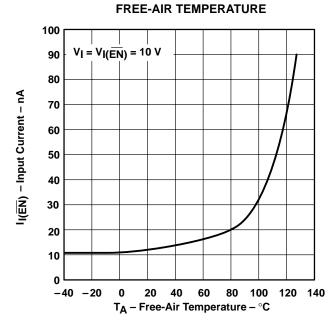


Figure 31



OUTPUT VOLTAGE RESPONSE FROM ENABLE (EN)

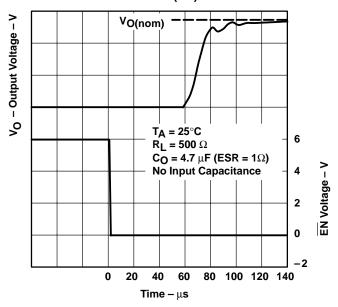


Figure 32

POWER-GOOD (PG) VOLTAGE

OUTPUT VOLTAGE

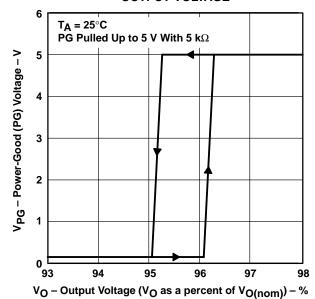


Figure 33

TYPICAL REGIONS OF STABILITY

COMPENSATION SERIES RESISTANCE

vs

OUTPUT CURRENT

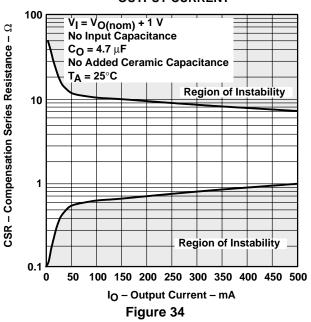
TYPICAL CHARACTERISTICS

100

0. 0 50

TYPICAL REGIONS OF STABILITY **COMPENSATION SERIES RESISTANCE**

vs **OUTPUT CURRENT**



CSR – Compensation Series Resistance – Ω $C_0 = 4.7 \,\mu\text{F} + 0.5 \,\mu\text{F}$ of **Ceramic Capacitance** T_A = 25°C Region of Instability

 $V_I = V_{O(nom)} + 1 V$

No Input Capacitance

IO - Output Current - mA Figure 35

TYPICAL REGIONS OF STABILITY **COMPENSATION SERIES RESISTANCE**

vs ADDED CERAMIC CAPACITANCE

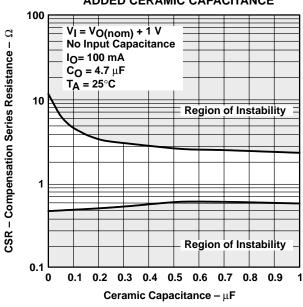


Figure 36

TYPICAL REGIONS OF STABILITY **COMPENSATION SERIES RESISTANCE**

vs

100 150 200 250 300 350 400 450 500

Region of Instability

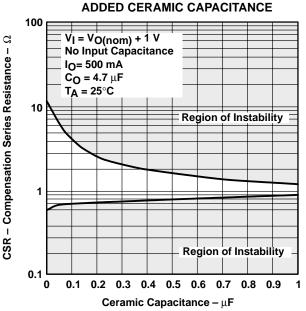


Figure 37



TYPICAL REGIONS OF STABILITY[†] COMPENSATION SERIES RESISTANCE vs

OUTPUT CURRENT

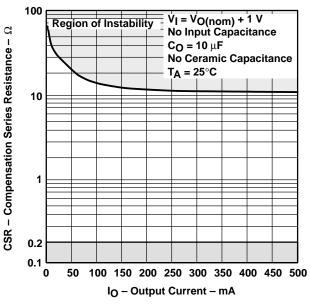


Figure 38

TYPICAL REGIONS OF STABILITY[†] COMPENSATION SERIES RESISTANCE

ADDED CERAMIC CAPACITANCE

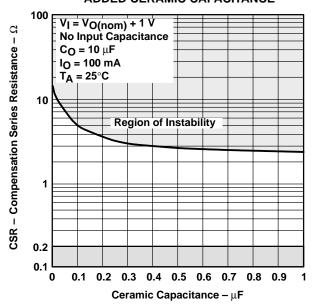
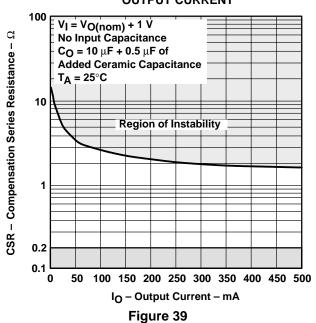


Figure 40

†CSR values below 0.1 Ω are not recommended.

TYPICAL REGIONS OF STABILITY[†] COMPENSATION SERIES RESISTANCE vs OUTPUT CURRENT



TYPICAL REGIONS OF STABILITY† COMPENSATION SERIES RESISTANCE

ADDED CERAMIC CAPACITANCE

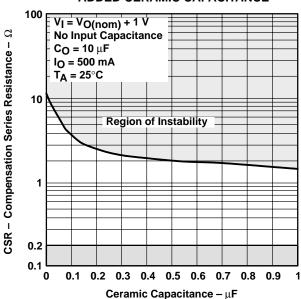
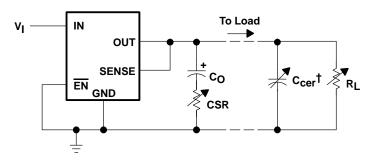


Figure 41



TYPICAL CHARACTERISTICS



†Ceramic capacitor

Figure 42. Test Circuit for Typical Regions of Stability (Figures 34 through 41)

TPS7101Q, TPS7133Q, TPS7148Q, TPS7150Q TPS7101Y, TPS7133Y, TPS7148Y, TPS7150Y LOW-DROPOUT VOLTAGE REGULATORS

SLVS092G - NOVEMBER 1994 - REVISED JANUARY 2003

APPLICATION INFORMATION

The TPS71xx series of low-dropout (LDO) regulators is designed to overcome many of the shortcomings of earlier-generation LDOs, while adding features such as a power-saving shutdown mode and a power-good indicator. The TPS71xx family includes three fixed-output voltage regulators: the TPS7133 (3.3 V), the TPS7148 (4.85 V), and the TPS7150 (5 V). The family also offers an adjustable device, the TPS7101 (adjustable from 1.2 V to 9.75 V).

device operation

The TPS71xx, unlike many other LDOs, features very low quiescent currents that remain virtually constant even with varying loads. Conventional LDO regulators use a pnp-pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). Close examination of the data sheets reveals that those devices are typically specified under near no-load conditions; actual operating currents are much higher as evidenced by typical quiescent current versus load current curves. The TPS71xx uses a PMOS transistor to pass current; because the gate of the PMOS element is voltage driven, operating currents are low and invariable over the full load range. The TPS71xx specifications reflect actual performance under load.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS71xx quiescent current remains low even when the regulator drops out, eliminating both problems.

Included in the TPS71xx family is a 4.85-V regulator, the TPS7148. Designed specifically for 5-V cellular systems, its 4.85-V output, regulated to within \pm 2%, allows for operation within the low-end limit of 5-V systems specified to \pm 5% tolerance; therefore, maximum regulated operating lifetime is obtained from a battery pack before the device drops out, adding crucial talk minutes between charges.

The TPS71xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to under 2 μ A. If the shutdown feature is not used, $\overline{\text{EN}}$ should be tied to ground. Response to an enable transition is quick; regulated output voltage is reestablished in typically 120 μ s.

minimum load requirements

The TPS71xx family is stable even at zero load; no minimum load is required for operation.

SENSE-pin connection

The SENSE pin of fixed-output devices must be connected to the regulator output for proper functioning of the regulator. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit (remote sense) to improve performance at that point. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network and noise pickup feeds through to the regulator output. Routing the SENSE connection to minimize/avoid noise pickup is essential. Adding an RC network between SENSE and OUT to filter noise is not recommended because it can cause the regulator to oscillate.

external capacitor requirements

An input capacitor is not required; however, a ceramic bypass capacitor (0.047 pF to 0.1 μ F) improves load transient response and noise rejection if the TPS71xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

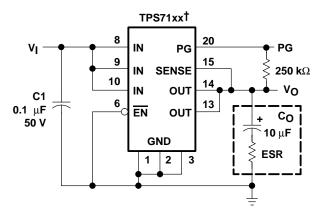


APPLICATION INFORMATION

external capacitor requirements (continued)

As with most LDO regulators, the TPS71xx family requires an output capacitor for stability. A 10- μ F solid-tantalum capacitor connected from the regulator output to ground is sufficient to ensure stability over the full load range (see Figure 43). Adding high-frequency ceramic or film capacitors (such as power-supply bypass capacitors for digital or analog ICs) can cause the regulator to become unstable unless the ESR of the tantalum capacitor is less than 1.2 Ω over temperature. Where component height and/or mounting area is a problem, physically smaller, 10- μ F devices can be screened for ESR. Figures 34 through 41 show the stable regions of operation using different values of output capacitance with various values of ceramic load capacitance.

In applications with little or no high-frequency bypass capacitance (< $0.2~\mu$ F), the output capacitance can be reduced to 4.7 μ F, provided ESR is maintained between the values shown in figures 34 through 41. Because minimum capacitor ESR is seldom if ever specified, it may be necessary to add a 0.5- Ω to 1- Ω resistor in series with the capacitor and limit ESR to $1.5~\Omega$ maximum.



† TPS7133, TPS7148, TPS7150 (fixed-voltage options)

Figure 43. Typical Application Circuit

programming the TPS7101 adjustable LDO regulator

Programming the adjustable regulators is accomplished using an external resistor divider as shown in Figure 44. The equation governing the output voltage is:

$$V_{O} = V_{ref} \cdot \left(1 + \frac{R1}{R2}\right)$$

where

 V_{ref} = reference voltage, 1.178 V typ

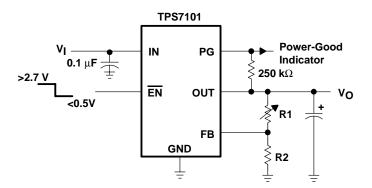


APPLICATION INFORMATION

programming the TPS7101 adjustable LDO regulator (continued)

Resistors R1 and R2 should be chosen for approximately 7- μ A divider current. A recommended value for R2 is 169 k Ω with R1 adjusted for the desired output voltage. Smaller resistors can be used, but offer no inherent advantage and consume more power. Larger values of R1 and R2 should be avoided as leakage currents at FB introduce an error. Solving equation 1 for R1 yields a more useful equation for choosing the appropriate resistance:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \cdot R2$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

T TOOTA MINING COIDE										
OUTPUT VOLTAGE	R1	R2	UNIT							
2.5 V	191	169	kΩ							
3.3 V	309	169	kΩ							
3.6 V	348	169	kΩ							
4 V	402	169	kΩ							
5 V	549	169	kΩ							
6.4 V	750	169	kΩ							

Figure 44. TPS7101 Adjustable LDO Regulator Programming

power-good indicator

The TPS71xx features a power-good (PG) output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the PG output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. PG can be used to drive power-on reset circuitry or as a low-battery indicator. PG does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low, relative to its nominal regulated value.

regulator protection

The TPS71xx PMOS-pass transistor has a built-in back diode that safely conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS71xx also features internal current limiting and thermal protection. During normal operation, the TPS71xx limits output current to approximately 1 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 165°C, thermal-protection circuitry shuts it down. Once the device has cooled, regulator operation resumes.







10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS7101QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7101QP	Samples
TPS7101QPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7101	Samples
TPS7101QPWLE	OBSOLETI	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 125		
TPS7101QPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7101	Samples
TPS7133QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7133QP	Samples
TPS7133QPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7133QP	Samples
TPS7133QPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7133	Samples
TPS7133QPWLE	OBSOLETI	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 125		
TPS7133QPWPLE	OBSOLETI	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 125		
TPS7133QPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7133	Samples



www.ti.com

PACKAGE OPTION ADDENDUM

10-Jun-2014

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS7148QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7148QP	Samples
TPS7148QPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7148QP	Samples
TPS7148QPWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 125		
TPS7150QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7150QP	Samples
TPS7150QPWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 125		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

10-Jun-2014

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

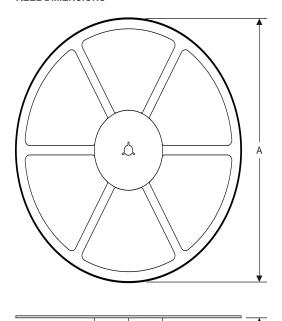
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS7101QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7101QPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS7133QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7133QPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS7148QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7150QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS7101QDR	SOIC	D	8	2500	367.0	367.0	35.0
TPS7101QPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TPS7133QDR	SOIC	D	8	2500	367.0	367.0	35.0
TPS7133QPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TPS7148QDR	SOIC	D	8	2500	367.0	367.0	35.0
TPS7150QDR	SOIC	D	8	2500	367.0	367.0	35.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom Amplifiers amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt <u>power.ti.com</u> Space, Avionics and Defense <u>www.ti.com/space-avionics-defense</u>

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors <u>www.ti.com/omap</u> TI E2E Community <u>e2e.ti.com</u>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>